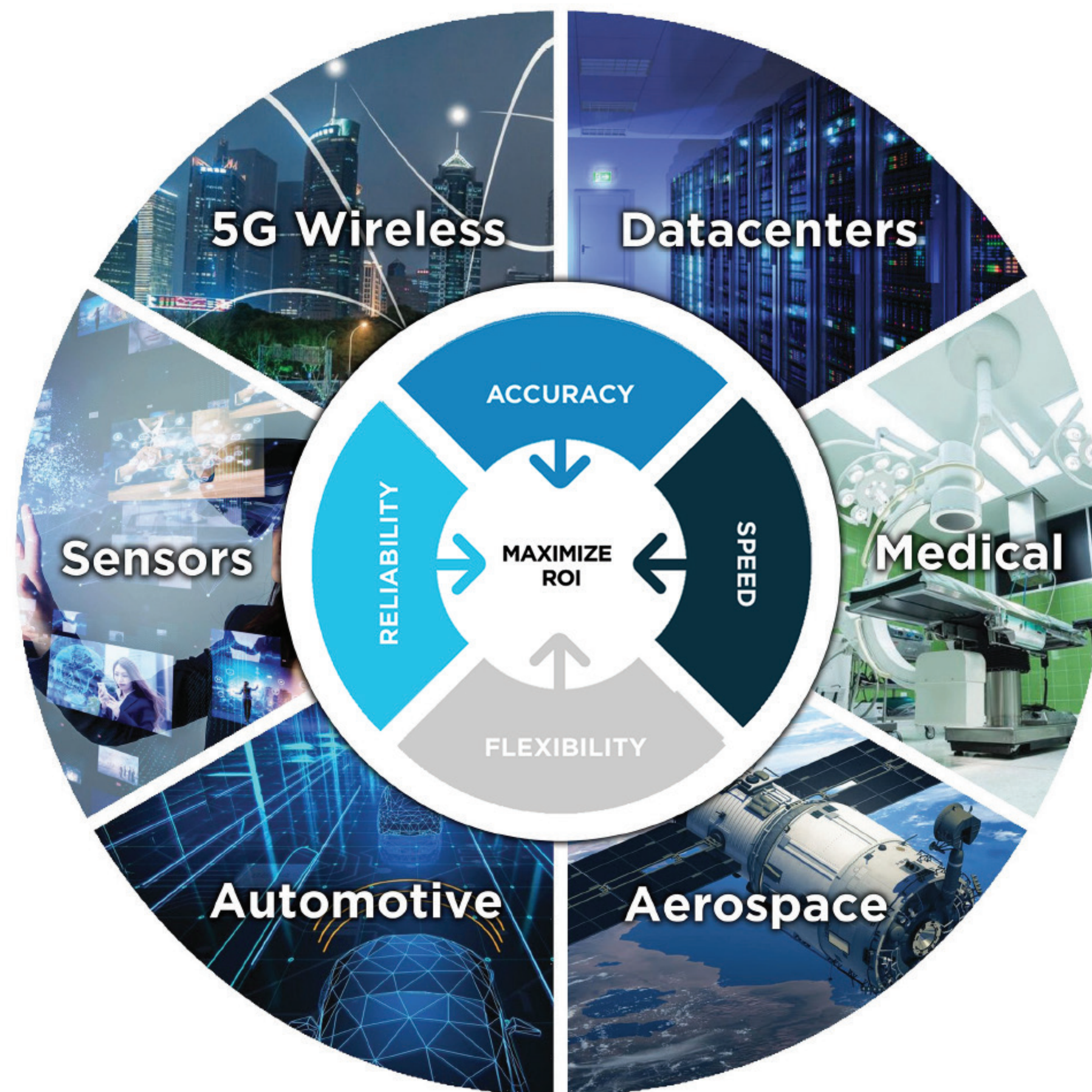
Bringing tomorrow's electronics to life



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MRSI MYCRONIC

mrsisystems.com

North America
554 Clark Rd
Tewksbury, MA USA 01876

Tel: +1 978 667 9449
Email: sales.mrsi@mycronic.com

MRSI China
101, Block A,
Huahan Innovation Park,
Langshan Road,
Shenzhen, China 518057

Tel: +86 755 26414155

MRSI EMEA
(Distributor and Demo Center)
Distek Strumenti & Misure Srl
Via Generale Giordano Orsini 42
80123 Napoli, Italy
marco@distek.it

Tel: +393483837815

MRSI Systems (a part of Mycronic Group) is the leading manufacturer of fully automated, high-speed, high-precision and flexible eutectic and epoxy die bonding systems. We offer solutions for research and development, low-to-medium volume production, and high-volume manufacturing of photonic devices such as lasers, detectors, modulators, AOCs, WDM/EML TO-Cans, Optical transceivers, LiDAR, VR/AR, sensors, silicon photonics, co-packaging optics, 3-D hybrid packaging, and optical imaging products. With 40+ years of industry experience and our worldwide local technical support team, we provide the most effective systems and assembly solutions for all packaging levels including chip-on-wafer (CoW), chip-on-carrier (CoC), PCB, and gold-box packaging. For more information visit www.mrsisystems.com

Mycronic is a Swedish high-tech company engaged in the development, manufacture and marketing of production equipment with high precision and flexibility requirements for the electronics industry. Mycronic's headquarters are located in Täby, north of Stockholm and the Group has subsidiaries in China, France, Germany, Japan, Mexico, the Netherlands, Singapore, South Korea, United Kingdom, the United States and Vietnam. Mycronic is listed on Nasdaq Stockholm. www.mycronic.com

Specifications are subject to change without notice.

202404_MRSI-705V3

MRSI MYCRONIC

MRSI-705
5 MICRON DIE BONDER

500N High Force Available

Patented turret for "on-the-fly" tool change

MRSI Systems has been serving optoelectronic and microelectronic customers for the past 40 years and understands their requirement to scale efficiently in today's fast-paced marketplace.

Applications are found across a wide range of market segments, such as life & health sciences, aerospace, defense, automotive, lighting, communications, and more.

MRSI's die bonding solutions help our customers to enable just-in-time supply and fast-pace innovations of critical components for high-growth market segments. The ultra-flexible MRSI-705 can be used for R&D prototyping to low/medium volume. With our optional patented turret for "on-the-fly" tool change, high volume can be achieved.

Our family of die bonding solutions are built with the same hardware and software platforms configured to minimize process deviations, reduce NPI cost, and increase ROI for customers with MRSI's long proven product reliability and global customer support.

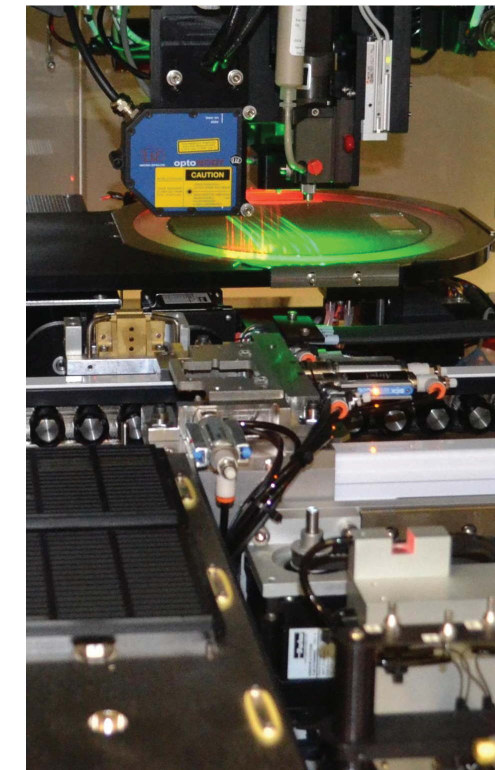
MRSI-705 Die Bonder Ultimate Flexibility

Assembly Technologies

- Eutectic Bonding
- Epoxy Die Attach
- In-situ UV Bonding
- Flip Chip Assembly
- Thermal Compression Bonding

All-In-One Platform

- Large Configurable Work Area
- Force Control for Advanced Assembly
- Advanced Machine Vision
- Programmable Multi-Color Lighting
- Quality Software, Computer and Motion Control
- Turnkey Integrated Production Lines

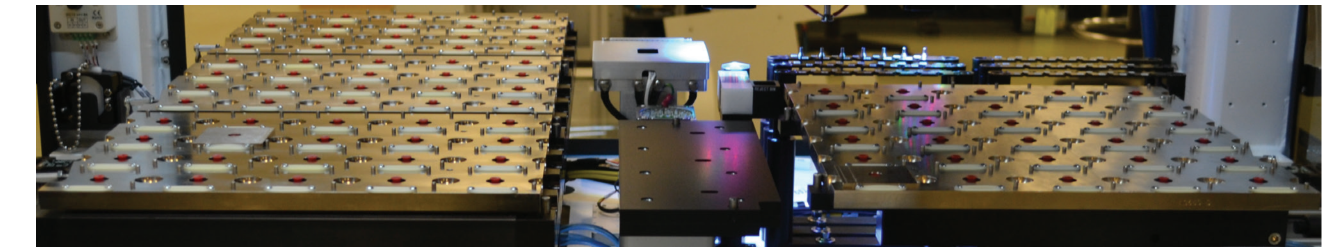


Configuration for Higher Volume

The MRSI-705 offers an optional patented turret for "on-the-fly" tool change to significantly increase the production volume from our machine without sacrificing flexibility. The patented turret has the capacity for 12 tools with zero tool change time.

This leads to increased machine efficiency, higher output and lower manufacturing costs.

Applications include processes requiring a large number of parts-specific tools, using eutectic bonding, and the need to assemble complex products with a multitude of component types.



Applications

- 3D Packaging
- Wafer Scale Packaging
- LED Assembly
- Microwave Modules
- Photonics Packaging
- RF Power Amplifiers
- Infrared Sensors
- Pressure Sensors
- MEMS Devices
- Semiconductor Packaging
- Hybrid Circuits
- Multichip Modules
- Pacemakers and Hearing Aids
- Medical Imaging
- Laser Diode Bonding
- Inkjet and Print Head
- System on a Chip
- System in a Package